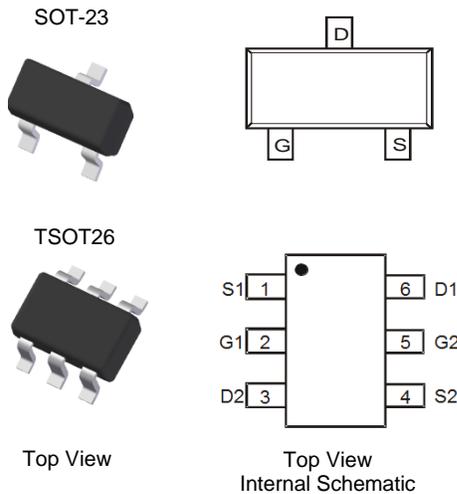


## Product Summary

$V_{(BR)DSS}$	$R_{DS(ON) \text{ max}}$	$I_D \text{ max}$ $T_A = +25^\circ\text{C}$
60V	1.8Ω @ $V_{GS} = 5V$	470mA
	2.4Ω @ $V_{GS} = 3V$	

## Description and Applications

DMN61D8L/LVT provides a single component solution for switching inductive loads such as relays, solenoids, and small DC motors in automotive applications, without the need of a freewheeling diode. DMN61D8L/LVT accepts logic level inputs, thus allowing it to be driven by logic gates, inverters, and microcontrollers. It is ideally suited for doors, windows, and antenna relay coils.



## Features and Benefits

- Provides a more reliable and robust interface between sensitive logic and DC relay coils.
- Replaces 3-4 discrete components enabling PCB footprint to be reduced.
- Internal active clamp removes the need for external zener diode.
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

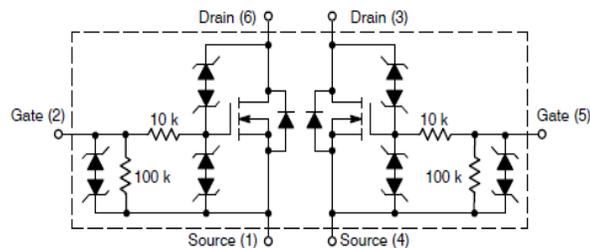
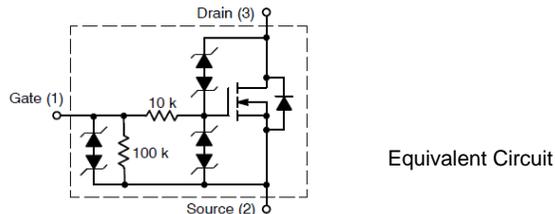
## Mechanical Data

### Case: SOT23

- Case Material: Molded Plastic, "Green" Molding Compound; UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – Matte Tin Annealed over Alloy 42 Leadframe. (Lead-Free Plating). Solderable per MIL-STD-202, Method 208@3
- Terminal Connections: See Diagram
- Weight: 0.008 grams (Approximate)

### Case: TSOT26

- Case Material: Molded Plastic, "Green" Molding Compound; UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals Connections: See Diagram
- Terminals: Finish – Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208@3
- Weight: 0.013 grams (Approximate)

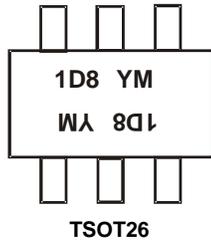
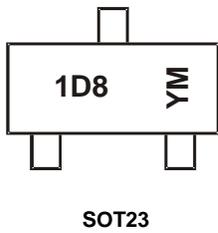


## Ordering Information (Note 4)

Part Number	Case	Packaging
DMN61D8L-7	SOT23	3,000/Tape & Reel
DMN61D8L-13	SOT23	10,000/Tape & Reel
DMN61D8LVT-7	TSOT26	3,000/Tape & Reel
DMN61D8LVT-13	TSOT26	10,000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
  2. See [http://www.diodes.com/quality/lead\\_free.html](http://www.diodes.com/quality/lead_free.html) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

## Marking Information



1D8 = Product Type Marking Code  
 YM = Date Code Marking  
 Y or  $\bar{Y}$  = Year (ex: C= 2015)  
 M = Month (ex: 9 = September)

### Date Code Key

Year	2014	2015	2016	2017	2018	2019	2020
Code	B	C	D	E	F	G	H

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

## Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units
Drain-Source Voltage	V <sub>DSS</sub>	60	V
Gate-Source Voltage	V <sub>GSS</sub>	±12	V
Continuous Drain Current (Note 6) SOT23	I <sub>D</sub>	470 370	mA
Continuous Drain Current (Note 6) TSOT26	I <sub>D</sub>	630 500	mA
Maximum Continuous Body Diode Forward Current (Note 6)	I <sub>S</sub>	0.5	A
Single Pulse Drain-to-Source Avalanche Energy (for relay coils/inductive loads of 80Ω or higher) (T <sub>J</sub> initial = +85°C)	E <sub>Z</sub>	200	mJ
Peak Power Dissipation, Drain-to-Source (non-repetitive current square pulse 1.0 ms duration) (T <sub>J</sub> initial = +85°C)	PPK	20	W
Load Dump Pulse, Drain-to-Source, R <sub>SOURCE</sub> = 0.5Ω, T = 300 ms (for relay coils/inductive loads of 80Ω or higher) (T <sub>J</sub> Initial = +85°C)	ELD1	60	V
Inductive Switching Transient 1, Drain-to-Source (Waveform: R <sub>SOURCE</sub> = 10Ω, T = 2.0 ms) (for relay coils/inductive loads of 80Ω or higher) (T <sub>J</sub> Initial = +85°C)	ELD2	100	V
Inductive Switching Transient 2, Drain-to-Source (Waveform: R <sub>SOURCE</sub> = 4.0Ω, T = 50 μs) (for relay coils/inductive loads of 80Ω or higher) (T <sub>J</sub> Initial = +85°C)	ELD3	300	V
Reverse Battery, 10 Minutes (Drain-to-Source) (for relay coils/inductive loads of 80Ω or higher)	Rev-Bat	-14	V
Dual Voltage Jump Start, 10 Minutes (Drain-to-Source)	Dual-Volt	28	V
ESD Human Body Model (HBM)	ESD	4,000	V

**Thermal Characteristics (SOT23)** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units
Total Power Dissipation (Note 5)	P <sub>D</sub>	390	mW
Thermal Resistance, Junction to Ambient (Note 5)	R <sub>θJA</sub>	321	°C/W
Total Power Dissipation (Note 6)	P <sub>D</sub>	610	mW
Thermal Resistance, Junction to Ambient (Note 6)	R <sub>θJA</sub>	208	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

**Thermal Characteristics (TSOT26)** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units
Total Power Dissipation (Note 5)	P <sub>D</sub>	820	mW
Thermal Resistance, Junction to Ambient (Note 5)	R <sub>θJA</sub>	154	°C/W
Total Power Dissipation (Note 6)	P <sub>D</sub>	1090	mW
Thermal Resistance, Junction to Ambient (Note 6)	R <sub>θJA</sub>	116	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS (Note 7)</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	60	—	—	V	V <sub>GS</sub> = 0V, I <sub>D</sub> = 10mA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	—	—	50 0.5	μA	V <sub>DS</sub> = 60V, V <sub>GS</sub> = 0V V <sub>DS</sub> = 12V, V <sub>GS</sub> = 0V
Gate-Source Leakage	I <sub>GSS</sub>	—	—	±90 ±60	μA	V <sub>GS</sub> = ±5V, V <sub>DS</sub> = 0V V <sub>GS</sub> = ±3V, V <sub>DS</sub> = 0V
<b>ON CHARACTERISTICS (Note 7)</b>						
Gate Threshold Voltage	V <sub>GS(th)</sub>	1.3	—	2.0	V	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 1mA
Static Drain-Source On-Resistance	R <sub>DS(on)</sub>	—	1.1 1.4	1.8 2.4	Ω	V <sub>GS</sub> = 5V, I <sub>D</sub> = 0.15A V <sub>GS</sub> = 3V, I <sub>D</sub> = 0.15A
Forward Transfer Admittance	Y <sub>fs</sub>	80	—	—	ms	V <sub>DS</sub> = 12V, I <sub>D</sub> = 0.15A
Diode Forward Voltage	V <sub>SD</sub>	—	—	1.2	V	V <sub>GS</sub> = 0V, I <sub>S</sub> = 0.15A
<b>DYNAMIC CHARACTERISTICS (Note 8)</b>						
Input Capacitance	C <sub>iss</sub>	—	12.9	—	pF	V <sub>DS</sub> = 12V, V <sub>GS</sub> = 0V f = 1.0MHz
Output Capacitance	C <sub>oss</sub>	—	17	—	pF	
Reverse Transfer Capacitance	C <sub>rss</sub>	—	0.84	—	pF	
Total Gate Charge	Q <sub>g</sub>	—	0.74	—	nC	V <sub>GS</sub> = 5V, V <sub>DS</sub> = 12V, I <sub>D</sub> = 150mA
Gate-Source Charge	Q <sub>gs</sub>	—	0.19	—	nC	
Gate-Drain Charge	Q <sub>gd</sub>	—	0.16	—	nC	
Turn-On Delay Time	t <sub>D(on)</sub>	—	131	—	ns	V <sub>DD</sub> = 12V, V <sub>GS</sub> = 5V.
Turn-On Rise Time	t <sub>r</sub>	—	301	—	ns	
Turn-Off Delay Time	t <sub>D(off)</sub>	—	582	—	ns	
Turn-Off Fall Time	t <sub>f</sub>	—	440	—	ns	

- Notes: 5. Device mounted on FR-4 PCB, with minimum recommended pad layout.  
6. Device mounted on 1" x 1" FR-4 PCB with high coverage 2oz. copper, single sided.  
7. Short duration pulse test used to minimize self-heating effect.  
8. Guaranteed by design. Not subject to product testing.

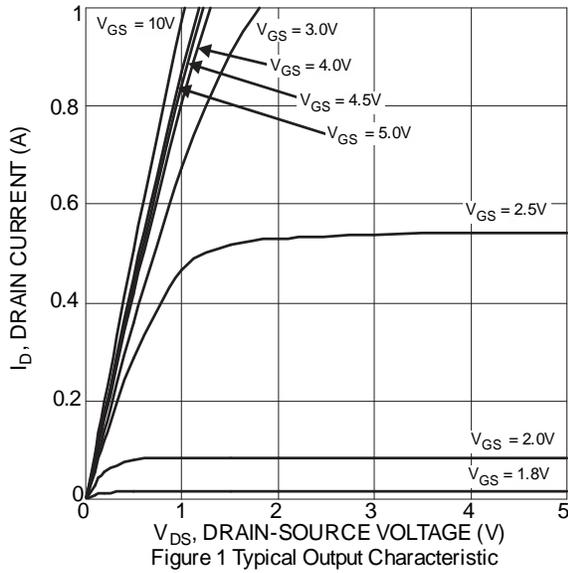


Figure 1 Typical Output Characteristic

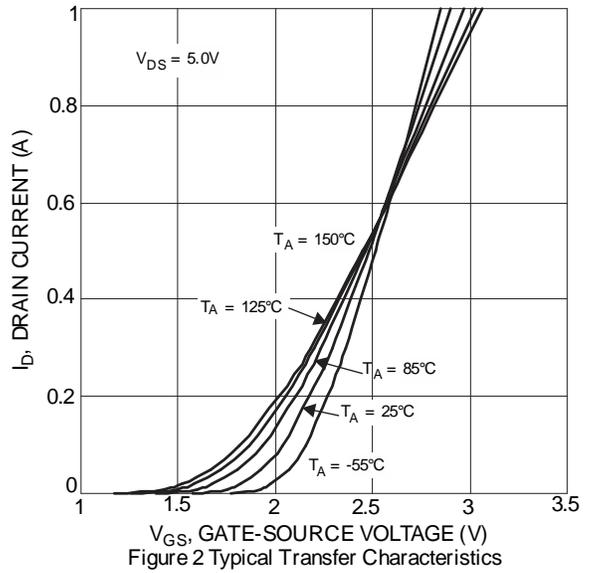


Figure 2 Typical Transfer Characteristics

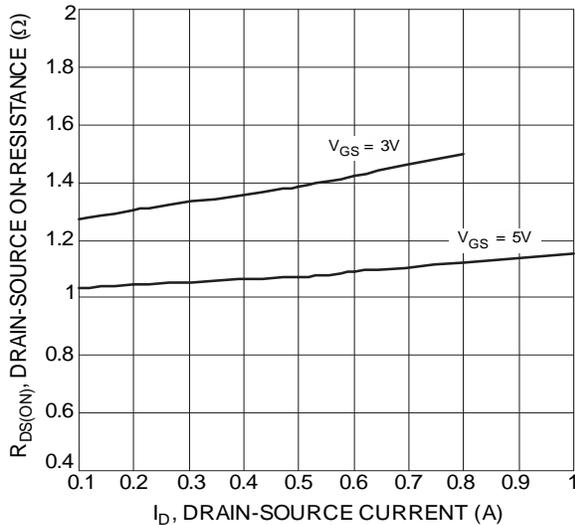


Figure 3 Typical On-Resistance vs. Drain Current and Gate Voltage

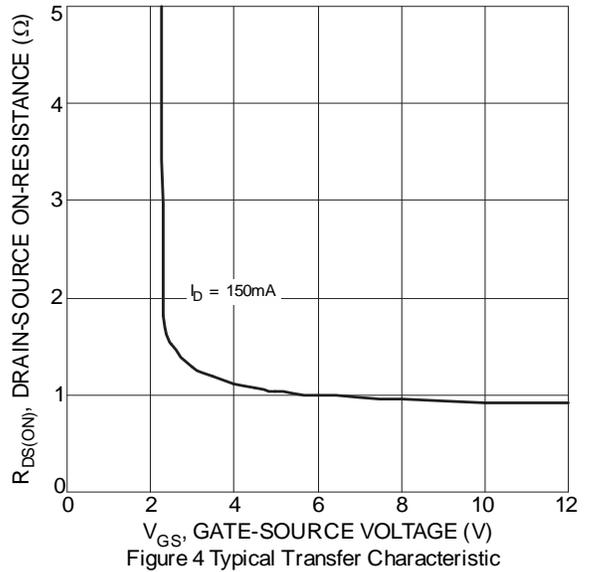


Figure 4 Typical Transfer Characteristic

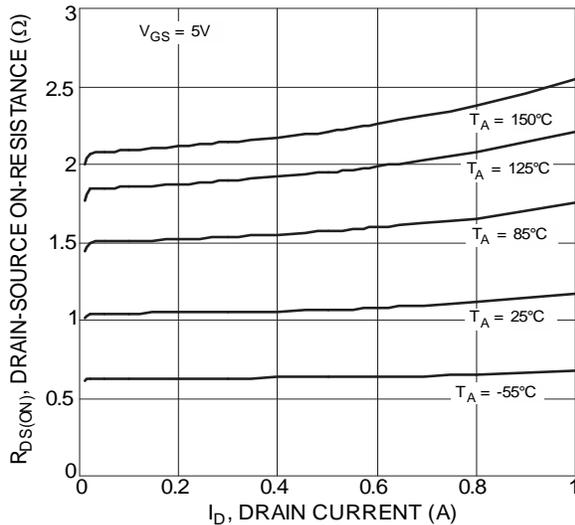


Figure 5 Typical On-Resistance vs. Drain Current and Temperature

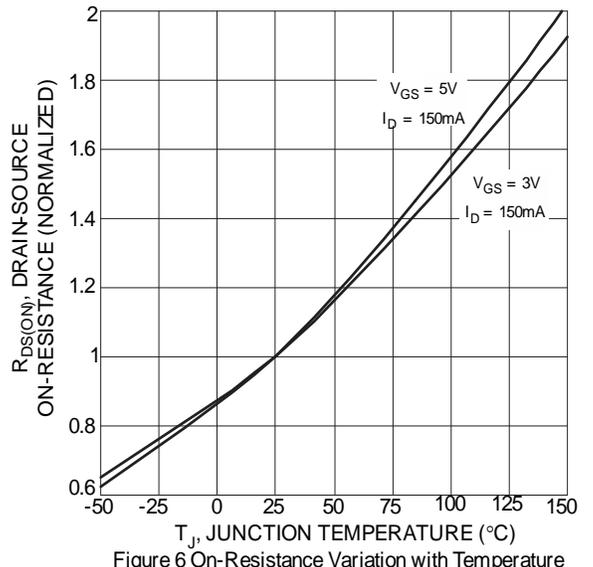


Figure 6 On-Resistance Variation with Temperature

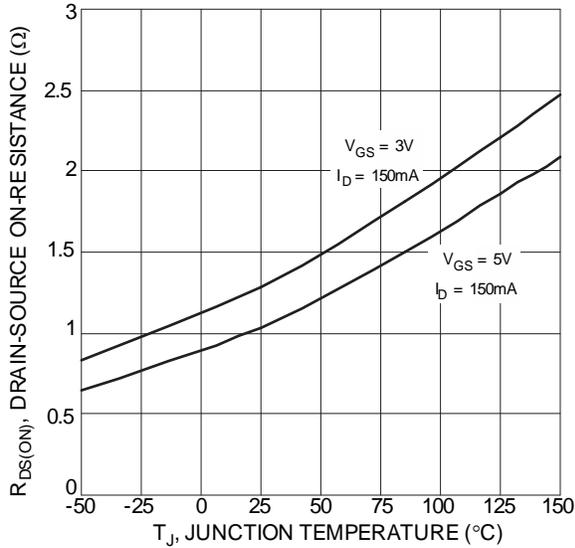


Figure 7 On-Resistance Variation with Temperature

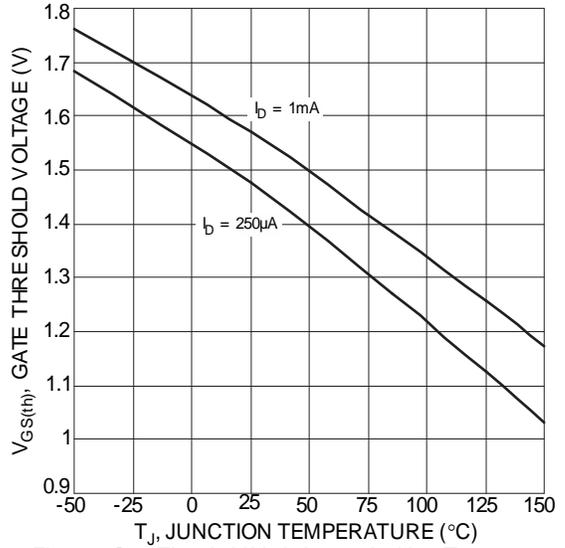


Figure 8 Gate Threshold Variation vs. Ambient Temperature

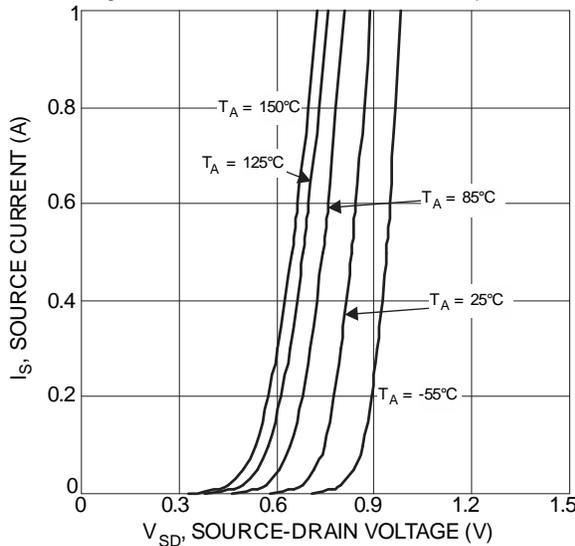


Figure 9 Diode Forward Voltage vs. Current

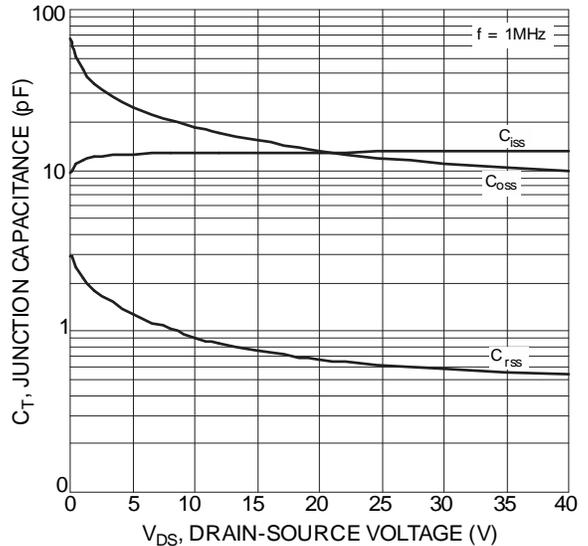


Figure 10 Typical Junction Capacitance

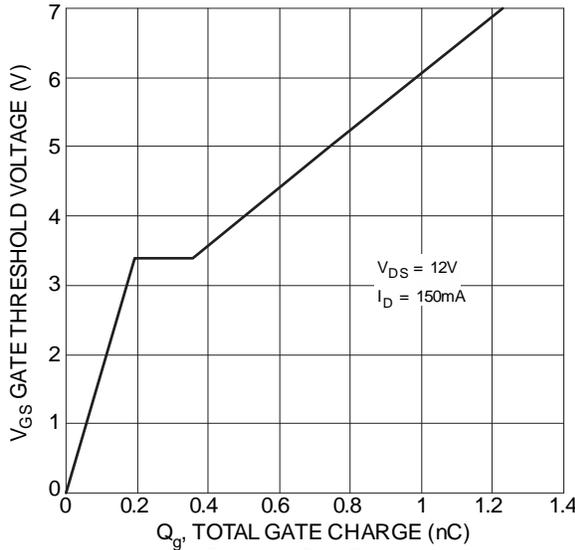


Figure 11 Gate Charge

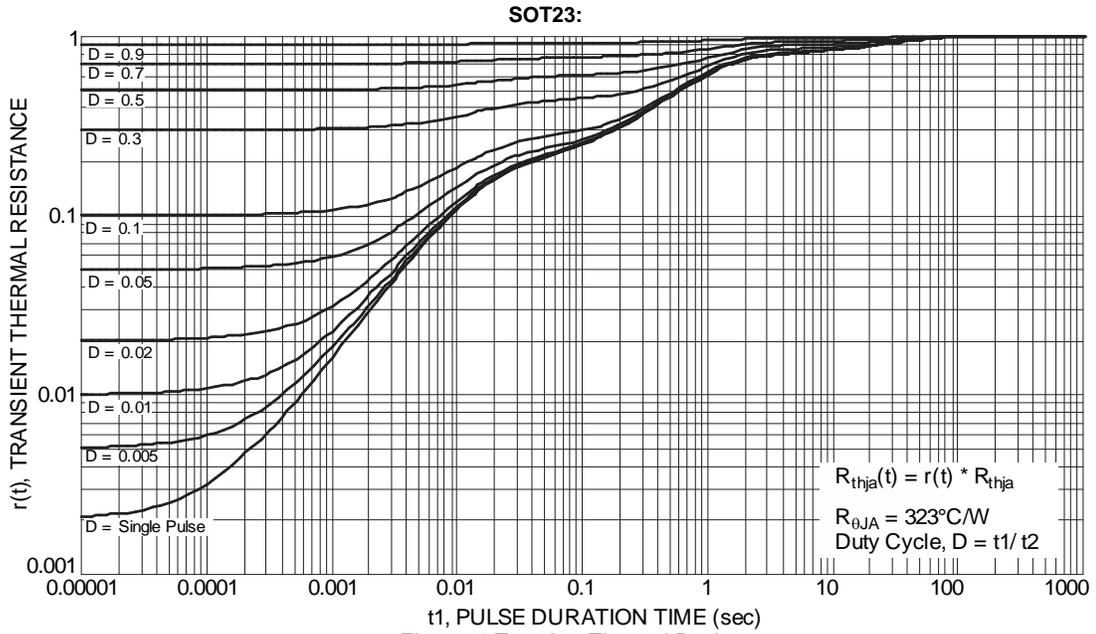


Figure 12 Transient Thermal Resistance

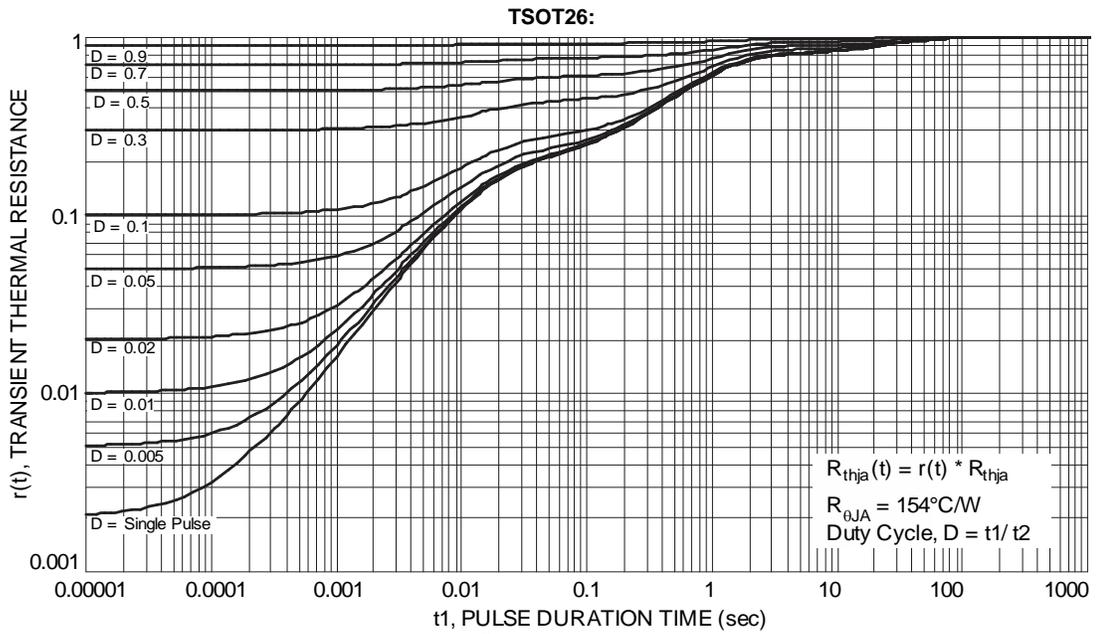
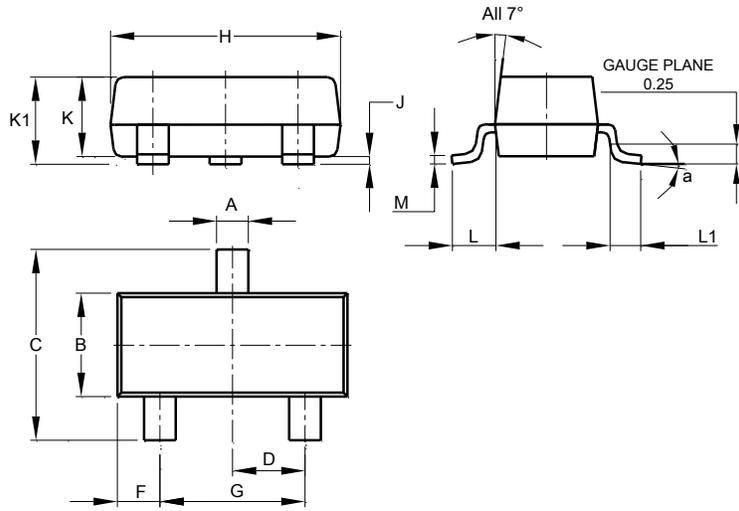


Figure 13 Transient Thermal Resistance

**Package Outline Dimensions**

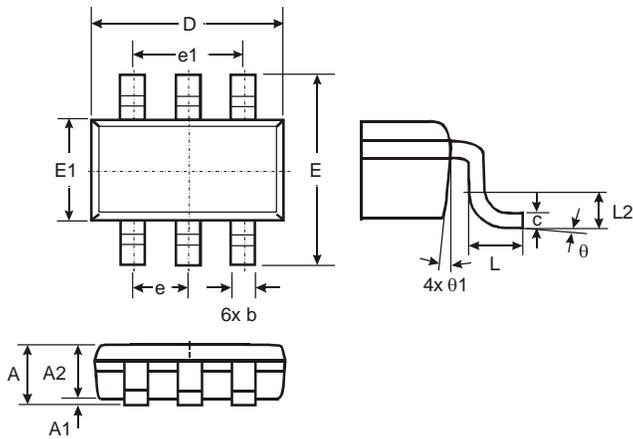
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.

**SOT23**



SOT23			
Dim	Min	Max	Typ
A	0.37	0.51	0.40
B	1.20	1.40	1.30
C	2.30	2.50	2.40
D	0.89	1.03	0.915
F	0.45	0.60	0.535
G	1.78	2.05	1.83
H	2.80	3.00	2.90
J	0.013	0.10	0.05
K	0.890	1.00	0.975
K1	0.903	1.10	1.025
L	0.45	0.61	0.55
L1	0.25	0.55	0.40
M	0.085	0.150	0.110
α	8°		
All Dimensions in mm			

**TSOT26**

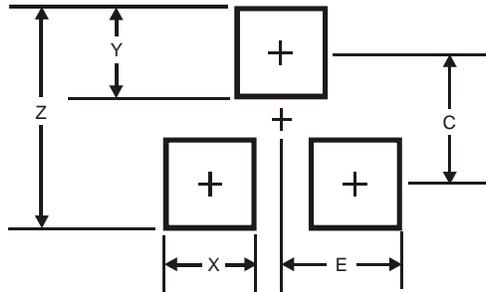


TSOT26			
Dim	Min	Max	Typ
A	-	1.00	-
A1	0.01	0.10	-
A2	0.84	0.90	-
D	-	-	2.90
E	-	-	2.80
E1	-	-	1.60
b	0.30	0.45	-
c	0.12	0.20	-
e	-	-	0.95
e1	-	-	1.90
L	0.30	0.50	-
L2	-	-	0.25
θ	0°	8°	4°
θ1	4°	12°	-
All Dimensions in mm			

**Suggested Pad Layout**

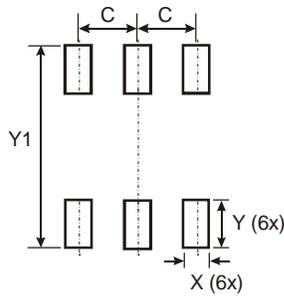
Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.

**SOT23**



Dimensions	Value (in mm)
Z	2.9
X	0.8
Y	0.9
C	2.0
E	1.35

**TSOT26**



Dimensions	Value (in mm)
C	0.950
X	0.700
Y	1.000
Y1	3.199

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